## Build Up HDI (Standard)

HDI06_1+4b+1_1,25_35_engl

**6 - Layers**

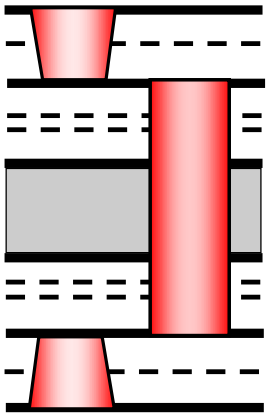
Core: 0,71 mm Cu 35/35 µm

**WE-Articel No.:**

**1 + 4B + 1**

**Customer:**

WÜRTH ELEKTRONIK

| layer description | | configuration | Raw-Material | CU | PREPREG | Final Thickness | Customer requirements |
|---|---|---|---|---|---|---|---|
| Customer | WE | | | | | [µm] | [µm] |
| | TOP/VS |  | Foil | 12 µm | 1) | 12 | |
| | | | | | 1 x 1080 | **60** | |
| | 2 | | Foil | 9 µm | | **30** | |
| | | | | | 2 x 1080 | **132** | |
| | 3 | | | 35 µm | | **33** | |
| | | | 0,710 mm | | | **710** | |
| | 4 | | | 35 µm | | **33** | |
| | | | | | 2 x 1080 | **132** | |
| | 5 | | Foil | 9 µm | | **30** | |
| | | | | | 1 x 1080 | **60** | |
| | BOT/RS | | Foil | 12 µm | 1) | 12 | |

1) copper thickness outer layers: appr. 55 µm

| | | | | | | | |
|---|---|---|---|---|---|---|---|
| total material thickness: | | | | | | 1244 | |

Note: Lamination thickness for Prepregs depending on layout characteristics.

| | | | | | | | | |
|---|---|---|---|---|---|---|---|---|
| **final lamination thickness:** | **1,25** | +/- | 0,10 | mm | | | Date: | Engineer: |
| thickness with electro plated Cu: | 1,34 | +/- | 0,13 | mm | | | | |
| total thickness with soldermask | 1,40 | +/- | 0,15 | mm | | | | |
| customer requirement | | +/- | | mm | point: | | | |

| prepared: on | by | checked: on | by | approved: on | by | revision | |
|---|---|---|---|---|---|---|---|
| 05.01.2006 | **S. Keller** | 04.05.2006 | M.Kress | 05.01.2006 | R. Schönholz | 00 | page: 15+ |